72X SERIES MLF / QFN / BCC / LGA / BGA / µBGA / CSP



Elastomer Interface Material Features

- Handles package sizes 3x3mm to 10x10mm
- Clam shell
- Compression Surface Mount
- Elastomer interface material
- Wedge guided pressure pad for direct Z axis pressure on the package during lid engagement

Sensata

Technologies

- HTOL Compatible
- Modular Design: Minimal components
- Adaptable to various package thickness
- Any pitch or pitch combination 0.4mm and greater
- Max I/0 = 250

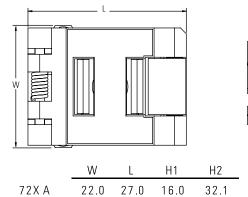


SPECIFICATIONS

Extremely High Frequency	>20GHz
Self Inductance	0.15nH
Mutual Inductance	0.04nH
Mutual Capacitance	0.013pF
Contact Resistance	< 50 mW
Current Rating	0.5 amps per I/O
Contact Force	18 grams
Extremely Coplanar	< 0.001"
Environmental Capability	- 40°C to 150°C
Typical Cycle Life	10,000 cycles min.

• Multiple Configurable Contact Sites per Pad





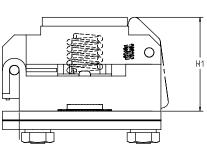
29.0

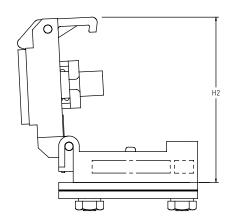
16.0

34.4

22.5

72X B







DESCRIPTION & ORDERING INFO

Sacket Series	<u>X</u>	XXX -	XX	X	X	G	X	x
Socket Series			_					
7: Molded Socket for MLF/QFN Pkgs 8: Molded Socket for BCC/LGA Pkgs 9: Molded Socket for BGA /µBGA/CSP Pkgs								
Package Size								
A: 3mm to 6mm pkg B: 7mm to 10mm pkg								
Lead Count								
Daakana Cira								
Package Size								
Size Configuration								
A-Z								
Package Shape								
S: Square R: Rectangle								
Pitch								
0: 1.27mm 1: 1.00mm 4: 0.40mm 5: 0.50mm 6: 0.65mm 7: 0.75mm 8: 0.80mm								
Package Variation								
Socket Size Variation								

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